

EAST - [03-1-3-03.wsp:1]										
File View Edit Tools Window Help										
<input checked="" type="checkbox"/> Drafts <input checked="" type="checkbox"/> BRS: 174/250-266.ccls. and <input checked="" type="checkbox"/> Pending <input checked="" type="checkbox"/> Active <input checked="" type="checkbox"/> L1: (22783) ((conductive adj paste) or paste or (paste adj material)) same <input checked="" type="checkbox"/> L2: (2103) 1 and (carrier or (carrier adj board)) <input checked="" type="checkbox"/> L3: (1227) 2 and (component or die or chip or IC)				<input type="button" value="Search"/> <input type="button" value="List"/> <input type="button" value="Browse"/> <input type="button" value="Queue"/> <input type="button" value="Clear"/> DBs: USPAT-EPO; JPO; DERVENT; USOCR <input type="checkbox"/> Plurals Default operator: OR <input type="checkbox"/> Highlight all hit terms initially 257/600-780.ccls. and 10						
<input type="button" value="BRS form"/> <input type="button" value="IS&R form"/> <input type="button" value="Image"/> <input type="button" value="Text"/> <input type="button" value="HTML"/>										
U	Document ID	Issue Dat	Page	Title	Current OR	Current XRe	Retrieval	Inventor	S	C
1	<input checked="" type="checkbox"/> US 6657124 R2	20031202		Advanced electronic package	174/52.4	257/690; 257/738-25	257/690; 257/738-25	Ho, Tony H.	<input type="checkbox"/>	<input type="checkbox"/>
2	<input checked="" type="checkbox"/> US 6630742 R2	20031007		Method for forming bumps, semiconductor device and a	257/772		257/772	Sakuyama, Seiki	<input type="checkbox"/>	<input type="checkbox"/>
3	<input checked="" type="checkbox"/> US 6586827 R2	20030701	18	Wiring board and method for fabrication the same	257/687	257/789; 257/793-	257/687	Takeuchi, Hiroki et al.	<input type="checkbox"/>	<input type="checkbox"/>
4	<input checked="" type="checkbox"/> US 6580169 R2	20030617		Method for forming bumps, semiconductor device and a	257/738	257/E21.508; 257/738	257/738	Sakuyama, Seiki et al.	<input type="checkbox"/>	<input type="checkbox"/>
5	<input checked="" type="checkbox"/> US 6555052 R2	20030429		Electron device and semiconductor device	420/560	257/772; 257/778-	257/772; 257/778-25	Soga, Tasao et al.	<input type="checkbox"/>	<input type="checkbox"/>
6	<input checked="" type="checkbox"/> US 6518163 R2	20030211		Method for forming bumps, semiconductor device and a	438/613	257/738; 257/738	257/738	Sakuyama, Seiki et al.	<input type="checkbox"/>	<input type="checkbox"/>
7	<input checked="" type="checkbox"/> US 6486551 R1	20021126		Wired board and method of producing the same	257/737	228/180.21; 228/180.22-	257/737; 257/738	Sato, Kazuhisa et al.	<input type="checkbox"/>	<input type="checkbox"/>
8	<input checked="" type="checkbox"/> US 6455785 R1	20020924	24	Bump connection with stacked metal balls	174/260	174/267; 228/180.22-	257/738	Sakurai, Hiroyuki et al.	<input type="checkbox"/>	<input type="checkbox"/>
9	<input checked="" type="checkbox"/> US 6429527 R1	20020806	7	Method and article for filling apertures in a high performance	257/774	257/773; 257/E23.075-	257/773; 257/774	Farquhar, Donald S. et al.	<input type="checkbox"/>	<input type="checkbox"/>
10	<input checked="" type="checkbox"/> US 6423154 R1	20020723		Solder-coating method, and solder paste suitable for use	148/24	228/248.1; 257/736-	257/736	Van Gerven, Johannes A. H. et al.	<input type="checkbox"/>	<input type="checkbox"/>
11	<input checked="" type="checkbox"/> US 6373717 R1	20020416	17	Electronic package with high density interconnect layer	361/795	174/255; 174/262-	257/698; 257/700	Downes, Jr., Francis J. et al.	<input type="checkbox"/>	<input type="checkbox"/>
12	<input checked="" type="checkbox"/> US 6369451 R2	20020409		Solder balls and columns with stratified underfills on a	257/779	257/737; 257/738-	257/737; 257/738-25	Lin, Paul T.	<input type="checkbox"/>	<input type="checkbox"/>
13	<input checked="" type="checkbox"/> US 6365978 R1	20020402		Electrical redundancy for improved mechanical reliability	257/786	257/693; 257/737-	257/693; 257/737-	Ibnabdelljalil, M'hamed et al.	<input type="checkbox"/>	<input type="checkbox"/>
14	<input checked="" type="checkbox"/> US 6351393 R1	20020226	12	Electronic package for electronic components and	361/795	174/252; 174/255-	257/642; 257/698-	Kresge, John S. et al.	<input type="checkbox"/>	<input type="checkbox"/>
15	<input checked="" type="checkbox"/> US 6323546 R1	20011127		Direct contact through hole type wafer structure	257/686	257/737; 257/738-	257/686; 257/737-25	Hsuan, Min Chih et al.	<input type="checkbox"/>	<input type="checkbox"/>
16	<input checked="" type="checkbox"/> US 6268239 R1	20010731		Semiconductor chip cooling structure and manufacturing	438/122	257/717; 257/719-	257/717; 257/719-	Ikeda, Renya	<input type="checkbox"/>	<input type="checkbox"/>
17	<input checked="" type="checkbox"/> US 6258449 R1	20010710	11	Low-thermal expansion circuit board and multilayer	428/209	174/257; 174/258-	257/702; 257/766-	Nagasawa, Megumu et al.	<input type="checkbox"/>	<input type="checkbox"/>
18	<input checked="" type="checkbox"/> US 6252300 R1	20010626		Direct contact through hole type wafer structure	257/686	257/777; 257/777-	257/686; 257/777-	Hsuan, Min-Chih et al.	<input type="checkbox"/>	<input type="checkbox"/>
19	<input checked="" type="checkbox"/> US 6235996 R1	20010522	14	Interconnection structure and process module assembly	174/257	174/261; 174/261-	257/737; 257/738-25	Farooq, Shaji et al.	<input type="checkbox"/>	<input type="checkbox"/>
20	<input checked="" type="checkbox"/> US 6137690 A R1	20001024	13	Electronic assembly	361/779	228/123.1; 228/180.21-	257/692; 257/737-	Carson, Robert Thomas et al.	<input type="checkbox"/>	<input type="checkbox"/>